PCB Assembly Materials

Reliability Delivered

Proven Halogen-Free Products for High-Reliability Applications

Indium8.9HF Solder Paste

- No dendritic growth
- Low-voiding on bottom termination components (ex. QFN, DPAK, and BGA)
- Supreme product stability with
 - Up to 60 hours stencil life
 - 12 months refrigerated storage
- · Compatible with different conformal coatings

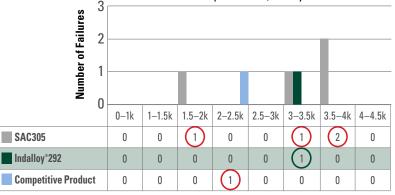


High-Reliability Alloy

Indalloy®292

- Outstanding -40/+150°C Thermal Cycling Performance through 3,000 Cycles
- Outstanding solder joint appearance without pinholes or blowholes

Thermal Cycling (-40/150°C) 0603 Capacitors 4,170 Cycles



Indalloy®292 has the least amount of failures (1) through 4,170 Cycles.

Contact our engineers: askus@indium.com

Learn more: www.indium.com

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From One Engineer To Another

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.





PCB Assembly Materials

Reliability Delivered

Improves Drop Shock Resistance

Durafuse[™] **LT**



Innovative Low-Temperature Alloy Technology

 Two orders of magnitude better drop shock performance compared to Bi-contained low-temperature options



Proven with Mycronic Testing

PicoShot™ NC-5M



High-Reliability Jetting Paste

- Eliminates head-in-pillow (HIP) defects
- · Compatible with Indium8.9HF Solder Paste series



· Eliminates graping



Optimized for Long-Term Jetting

Indium12.8HF NEW



MicroDispense and Jetting Paste

- Exceptional nanodispense and jetting performance
- Compatible with Indium8.9HF Solder Pastes series
- No-clean paste meets IPC J-STD-004B with Amendment 1 ROLO requirements
- · Exceptional electrical reliability

Exceptional Stencil Printing Performance

Indium6.6HF



Pb-Free and SnPb Solder Paste

- Low-voiding water-soluble flux
- · Wide reflow process window
- · Exceptional printing process window
- · Excellent wetting on a variety of surface finishes



Recommended PCBA Alloy

Indalloy®291



Drop-In Replacement for Sn100C®

- · Low dross creation rate
- · Low-cost of ownership—no Ag
- · Creates shiny, aesthetically pleasing solder joints
- · Available in solder bar and cored wire



Form No. 99799 R0

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